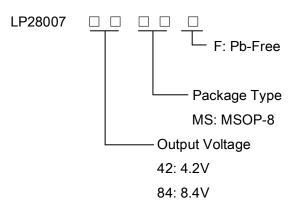
## Single and Dual Cell Li+ Battery Charger IC – LP28007

### **General Description**

The LP28007 is a fully integrated low cost single-cell Li-Ion battery charger IC ideal for portable applications. The LP28007 is capable of being powered up from AC adapter. The LP28007 enters sleep mode when AC adapter is removed. The LP28007 optimizes the charging task by using a control algorithm including preconditioning mode, fast charge mode and constant voltage mode. The charging task is terminated as the charge current drops below the preset threshold. The AC adapter charge current can be programmed up to 1A with an external resister. The internal thermal feedback circuitry regulates the die temperature to optimize the charge rate for all ambient temperatures. The LP28007 features 18V maximum rating voltages for AC adapter. The other features is under voltage protection.

### **Order Information**



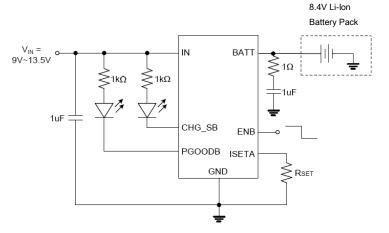
### **Applications**

- ♦ Portable Media Players/MP3 players
- ♦ Cellular and Smart mobile phone
- ♦ PDA/DSC
- ♦ Bluetooth Applications

### **Features**

- 18V Maximum Rating for AC Adapter
- Internal Integrate P-MOSFETs
- AC Adapter Power Good Status Indicator
- Charge Status Indicator
- Under Voltage Protection
- Automatic Recharge Feature
- Battery Temperature Monitoring
- Small 8-Lead MSOP(EP) Package
- Thermal Feedback Optimizing Charge Rate
- ROHS Compliant and 100% Lead (Pb)-Free

## **Typical Application Circuit**



### **Marking Information**

Device	Marking	Package	Shipping
LP28007	LPS	SP:MSOP-8	3K/REEL
	LP28007		
	XXXX		

## **Functional Pin Description**

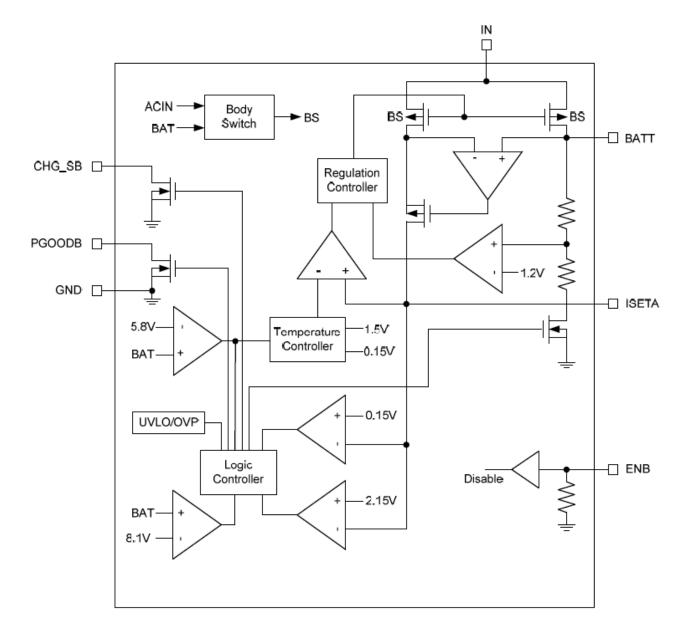
Package Type	Pin Configurations		
EMSOP- 8	ACIN 1 CHG_S 2 9 PGOOD 3 PGND 6 EN GND 4 5 ISETA		

## **Pin Description**

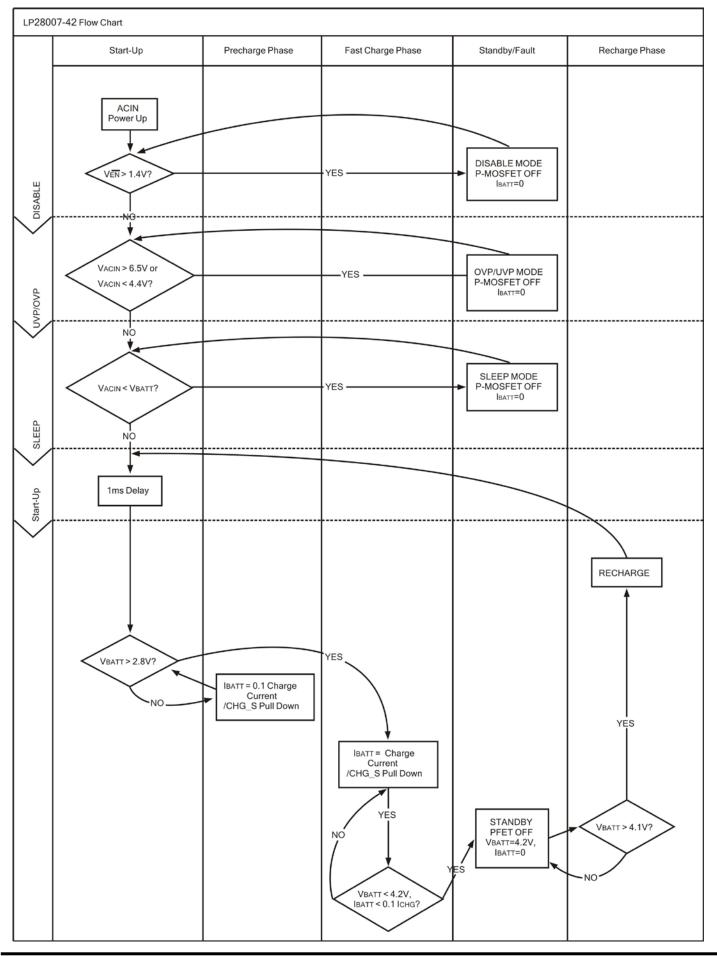
Pin No	Pin Name	Pin Function	
1	ACIN	Wall Adaptor Charge Input Supply.	
2	CHG_S	Charge Status Indicator Output (Open Drain).	
3	PGOOD	Power Good Indicator Output (Open drain).	
4	GND	Ground.	
5	ISETA	Wall Adaptor supply charge current Set point.	
6	EN	Charge Enable Input (active low).	
7	NC	No Internal Connection.	
8	BATT	Battery Charge Current Output.	
		This pin provides charge current to the battery and regulates the final float voltage to 4.2 or 8.4V. An internal precision resistor divider from this pin sets the float voltage which is disconnected in shutdown mode.	
9(Exposed Pad)	PGND	Exposed Pad Should be soldered to PCB Board and	
		Connected to GND.	

Note: LP28007-42MSF and LP28007-84MSF of Battery (Pin8) is output pin, the pin connects to Battery.

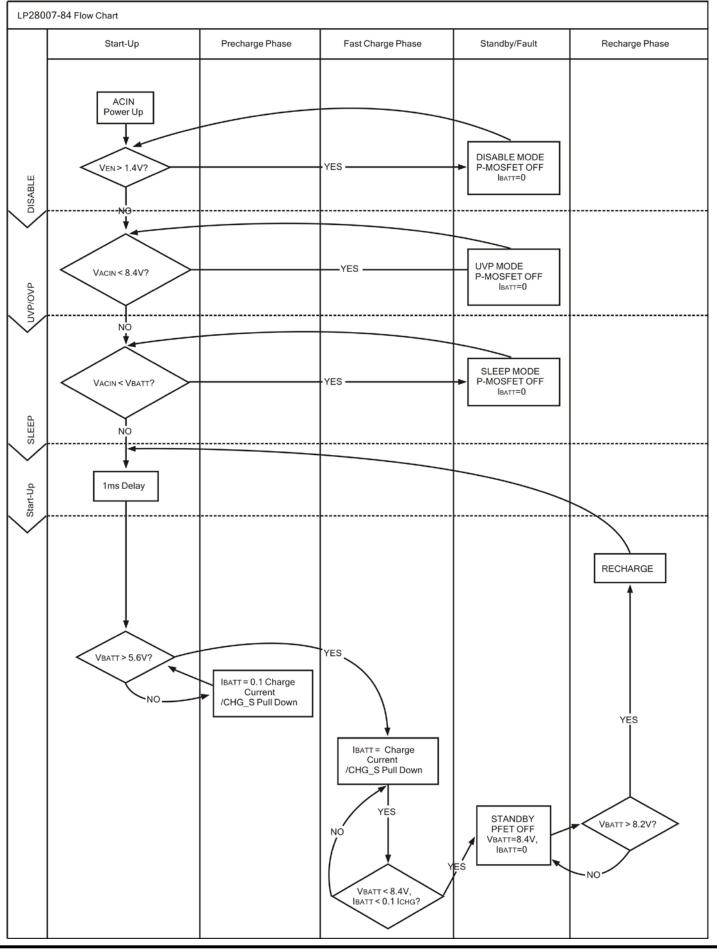
## **Function Block Diagram**



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## Absolute Maximum Ratings (Notes 1.2)

Vin,Vbatt,Vchgsb,Vpgood,Ven	-0.3V to 18V
Storage Temperature Range	-65°C to 150°C
VISETA	0.3V to 3.6V
Junction Temperature (TJ)	150°C
Lead Temperature (soldering, 10 sec.)	260°C

## Operating Ratings (Note 1, 2)

Supply Voltage	4.5V to 13.5V
Thermal Resistance( $\boldsymbol{ extbf{ heta}}$ JA, Note 3))	20°C/W
Operating Temperature Range	-40°C to 85°C
Thermal Resistance( $ heta$ JA, Note 4))	8.5°C/W

### **Electrical Characteristics**

### (TA=25°C, VIN=10V; unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
VIN	Input Operating Voltage Range		9		15	V
		Charge Mode. RSET=30K		300		uA
	Innut Supply Surrent	Standby Mode (Charge Terminated)		250		UA
Icc	Input Supply Current	Shutdown Mode (RSET Not Connected VIN < VBATT or VIN < Vuv)		190		uA
VFLOAT	Regulated Output(Float) Voltage	0°C ≦ TA ≦ 85°C	8.316	8.4	8.484	V
IBATT BATT Pin		RSET=1.5k,Current Mode		500		mA
	BATT Pin Current	RSET=0.75k,Current Mode		1000		mA
		Standby Mode, VBATT=8.4V	-1	0	1	uA
		Shutdown Mode	-1	0	1	uA
		Sleep Mode, VIN=0V	-1	0	1	uA
		VBATT <vtrickle, RSET=1.5K</vtrickle, 		60		mA
ITRICKLE	Trickle Charge Current	VBATT <vtrickle, RSET=0.75K</vtrickle, 		120		mA
VTRICKLE	Trickle Charge Threshold Voltage	RSET=1.5K, VBATT Rising		5.8		V

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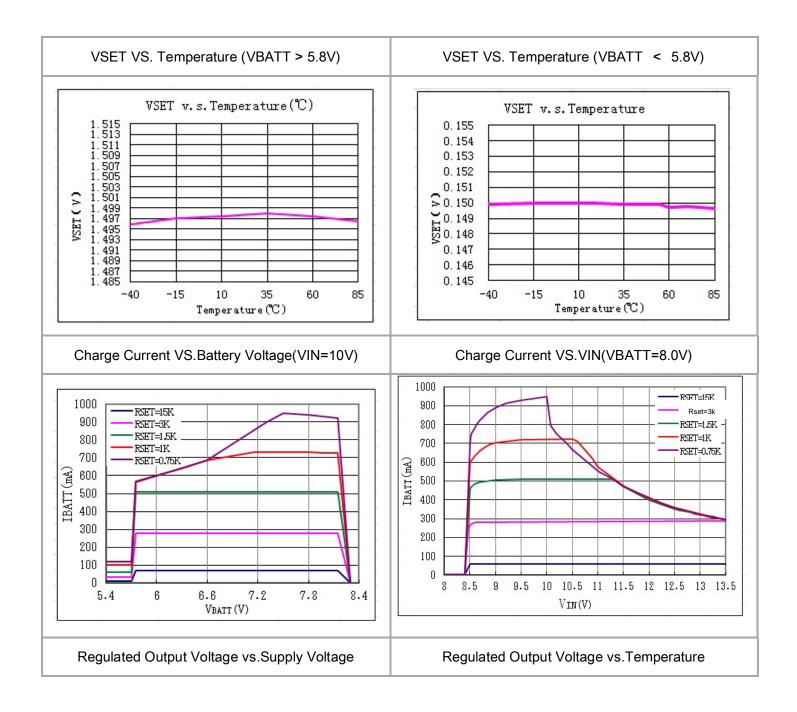
LP28007

V TRHYS	Trickle Charge Hysteresis Voltage	RSET=1.5K	250	mV
	Manual Shutdown Threshold	ISETA Pin Rising	2.15	V
VMSD	Voltage	ISETA Pin Falling	2.05	V
	VIN – VBATT Lockout	Vin from High to Low	30	mV
VASD	Threshold Voltage	Vin from Low to High	60	mV
	C/10Termination Current	RSET=1.5K	0.1	mA/ mA
ITERM Threshold		RSET=0.75K	0.1	mA/ mA
VSET	ISETA pin Voltage	RSET=1.5K,Current Mode	1.5	V
ICHG_SB	CHG_SB Pin Weak Pull-Down Current	VCHG_SB=5.0V	25	uA
VCHG_SB	CHG_SB Pin Output Low Voltage	ICHG_SB=5mA	0.35	V
VPGOOD	PGOOD Pin Output Low Voltage	IPGOOD_SB=5mA	0.35	V

Parameter		Symbol	Test Conditions	Min	Тур	Max	Units
Precharge	Precharge						
BATT Pre-Charge Risi	ng Threshold	VPRECH		2.6	2.8	3	V
BATT Pre-Charge Thre	eshold Hysteresis	∆VPRECH		50	100	200	mV
Pre-Charge Current		IPCHG	VBATT=2V	8	10	12	%
Recharge Threshold							
BATT Pre-Charge Falling Threshold Hysteresis		∆VPRECH_L	VREG – VBATT	60	100	150	mV
Charge Termination De	etection						
Termination Current R	atio(default)	ITERM	VBATT=4.2V		10		%
Logic Input/Output							
CHG_S Pull Down Voltage		VCHG_S	TBD, ICHG_S=5mA		65		mV
PGOOD Pull Down Voltage		VPGOOD	TBD, IPGOOD=5mA		220		mV
	Logic-High Voltage	VIH		1.5			V
EN Threshold	Logic-Low Voltage	VIL				0.4	V
EN Pin Input Current		IEN	IEN=2V			2	μA
Protection							
Thermal Regulation					125		°C

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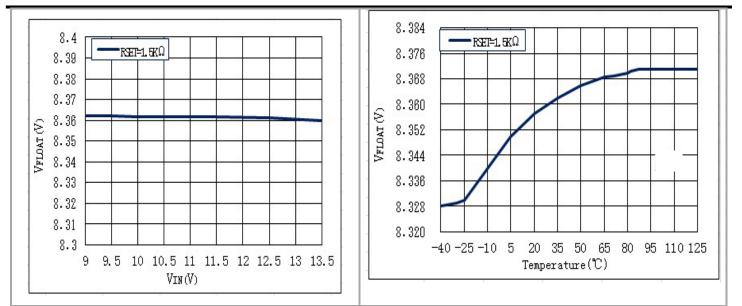
- Note 1. Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.
- Note 2. θJA Is measured in the natural convection at TA=25°C on a high effective thermal conductivity test board 4 layers,1S of JEDEC 51-7 thermal measurement standard. The case point of θJc is on the expose pad for the package.
- Note 3. Devices are ESD sensitive. Handling precaution is recommended.
- Note 4. The device is not guaranteed to function outside its operating conditions.



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### **Preliminary Datasheet**

LP28007



### **Application Information**

#### **Automatically Power Source Selection**

The LP28007 is a battery charger IC which is designed for Li-ion Battery with 4.2V rated voltage.

ACIN Mode : When the ACIN input voltage is higher than the UVP voltage level (4.4V), the LP28007 will turn on ACINP-MOSFET. Sleep Mode : The LP28007 will enter Sleep Mode when ACIN input voltage are removed. This feature provides low leakage current from the battery during the absence of input supply.

### **Fast-Charge Current Setting**

The LP28007 offers ISETA pin to determine the ACIN charge rate from 100mA to 1200mA. The charge current can be calculated as following equation.

$$I_{charge_ac} = K_{SET} \frac{V_{SET}}{R_{SETA}}$$

### Pre- Charge Current Setting

During a charge cycle if the battery voltage is below the VPRECH threshold, the LP28007 applies a pre-charge mode to the battery. This feature revives deeply discharged cell sand protects battery life. The LP28007 internal determines the pre-charge rate as 10% of the fast-charge current.

### **Battery Voltage Regulation**

The LP28007 monitors the battery voltage through the BATT pin. Once the battery voltage level closes to the VREG threshold, the LP28007 voltage enters constant phase and the charging current begins to taper down. When battery voltage is over the VREG threshold, the LP28007 will stop charge and keep to monitor the battery voltage. However, when the battery voltage decreases 100mV below the VREG, it will be recharged to keep the battery voltage. Charge Status Outputs. The open-drain CHG\_S and PGOOD outputs indicate various charger operations as shown in the following table. These status pins can be used to drive LEDs or communicate to the host processor. Note that ON indicates the open-drain transistor is turned on and LED is bright.

Charge State		CHG_S	PGOOD
ACIN	Charge	ON	ON
ACIN	Charge done	OFF	ON

#### **Temperature Regulation and Thermal Protection**

In order to maximize the charge rate, the LP28007 features a junction temperature regulation loop. If the power dissipation of the IC results in a junction temperature greater than the thermal regulation

threshold (125°C), theLP28007 throttles back on the charge current in order to maintain a junction temperature around the thermal regulation threshold (125°C). The LP28007 monitors the junction temperature, TJ, of the die and disconnects the battery from the input if TJ exceeds 125°C. This operation continues until junction temperature falls below thermal regulation threshold (125°C) by the hysteresis level. This feature prevents the chip from damage.

#### Selecting the Input and Output Capacitors

In most applications, the most important is the high-frequency decoupling capacitor on the input of the LP28007.A 1uF ceramic capacitor, placed in close proximity to input pin and GND pin is recommended. In some applications depending on the power supply characteristics and cable length, it may be necessary to add an additional 10uFceramic capacitor to the input.

The LP28007 requires a small output capacitor for loop stability. A 1uF ceramic capacitor placed between the BATT pin and GND is typically sufficient.

### Layout Consideration

The LP28007 is a fully integrated low cost single-cell Li-Ion battery charger ideal for portable applications. Careful PCB layout is necessary. For best performance, place all peripheral components as close to the IC as possible. A short connection is highly recommended. The following guide lines should be strictly followed when designing a PCB layout for the LP28007.Input capacitor should be placed close to IC and connected to ground plane.

The trace of input in the PCB should be placed far away the sensitive devices or shielded by the ground.

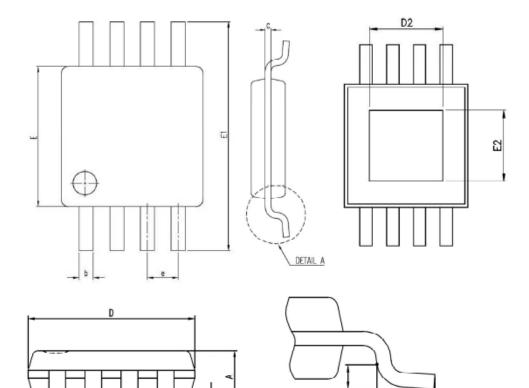
The GND should be connected to a strong ground plane for heat sinking and noise protection. The connection of RSETA should be isolated from other noisy traces.

The short wire is recommended to prevent EMI and noise coupling.

Output capacitor should be placed close to IC and connected to ground plane to reduce noise coupling. When PCB has poor layout, the 10uF is recommended to prevent noise.

## **Packaging Information**

E-MSOP-8L



SYMBOLS	MIN.	MAX.	
А	0.81	1.10	
A1	0.00	0.15	
b	0.22	0.38	
с	0.08	0.23	
D	2.90	3.10	
D2	1.42	1.78	
Е	2.90	3.10	
E1	4.80	5.00	
E2	1.38	1.73	
e	0.65 BSC.		
L	0.40	0.80	

UNIT: MM

0.25 NN

<u>DETAIL A</u>